



Media Release

UTAC Introduces New Grid Array QFN Package for High Density Applications

Singapore, 11 November 2014 – UTAC Holdings Ltd (UTAC), a Singapore-based semiconductor testing and assembly services provider, today announced that its new Grid Array Flat No-Lead (GQFN) package has received customer qualification and is moving to high volume production in Thailand in 1Q15.

UTAC has developed and integrated key new processes and design rules into the mature QFN platform technology to create the GQFN package. GQFN offer several advantages over conventional QFN or QFP packages with a 40 to 60% reduction in package size, with improved electrical performance through lower inductance and capacitance (Figure 2). GQFN technology enables lead frame based packages to deliver full array interconnect density providing customers with a lower cost alternative for devices that to date would require a fine pitch ball grid array (FBGA) or a wafer level chip scale package (WLCSP) technology.

UTAC has developed and qualified a broad technology platform in GQFN including: wire bond, flip chip, stacked die and system in a package (SiP) integration capabilities. This makes the package an ideal choice for many new applications used in mobile communications, automotive, industrial, computing and consumer supporting analog, mixed signal, logic, MEMS sensor and RF devices.

UTAC is an early pioneer in development and production of QFN packages, with 17 years of track record as illustrated in Figure 1, and is today one of the largest QFN package producers globally, shipping around 4 billion units per year.

UTAC delivered a presentation on GQFN and its applications to industry professionals at the recently concluded IMAPS Conference in San Diego in 14-16 October 2014.

~End~

Appendix

Figure 1: UTAC leadless lead frame milestones

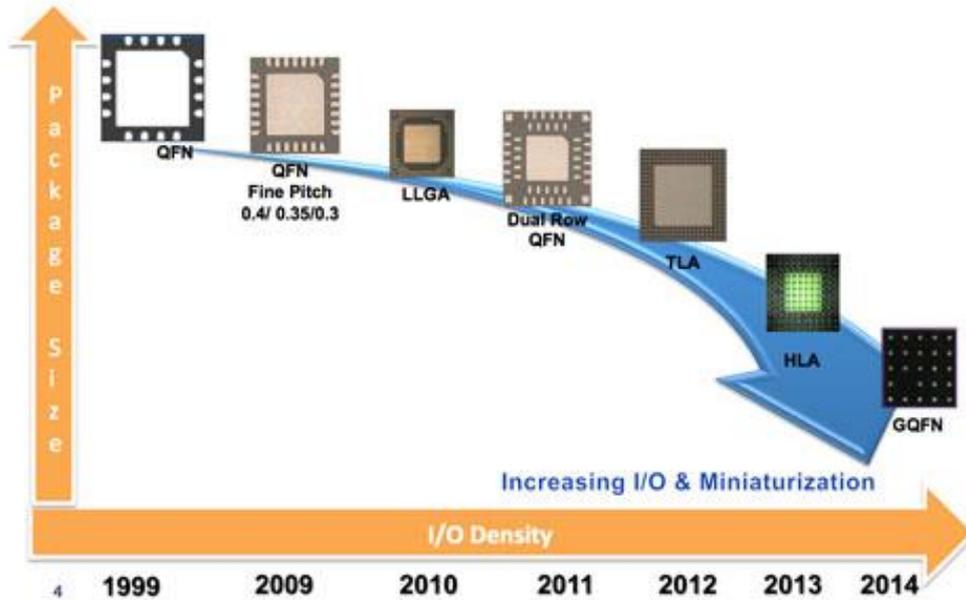
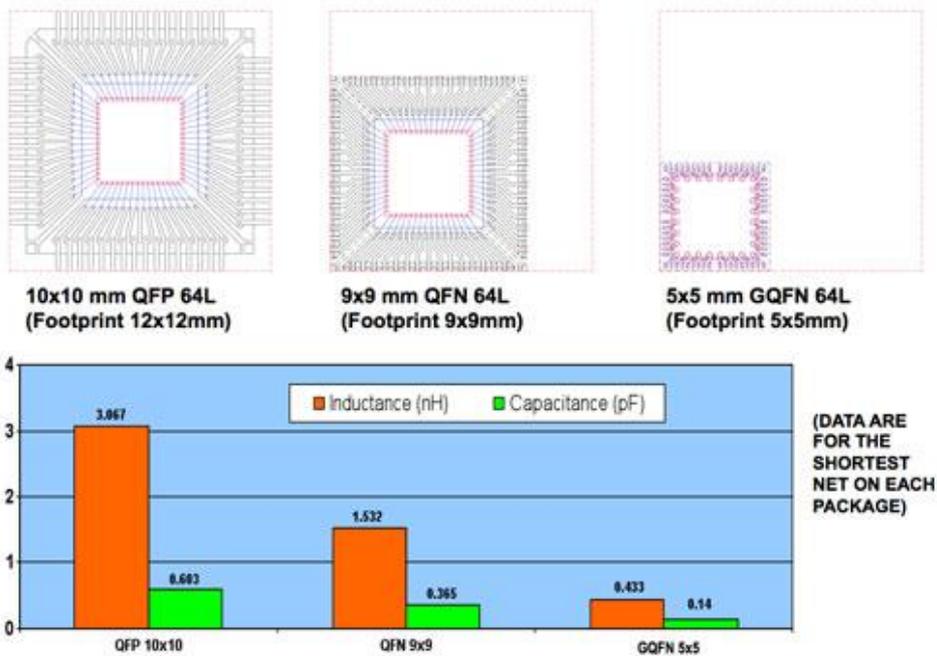


Figure 2: Electrical performance comparison: QFP/QFN/GQFN



About UTAC Holdings Ltd

UTAC Holdings Ltd (UTAC) is a leading independent provider of semiconductor assembly and testing services for a broad range of integrated circuits including memory, mixed-signal, analog, logic and radio frequency ICs. The Company offers a full range of package and test development, engineering and manufacturing services and solutions to a worldwide customer base, comprising integrated device manufacturers (IDMs), fabless companies and wafer foundries. UTAC operates manufacturing facilities in Singapore, Thailand, Taiwan, Malaysia, Indonesia and China, in addition to its global network of sales offices in the United States, Europe, Japan, Korea, China and Singapore.

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